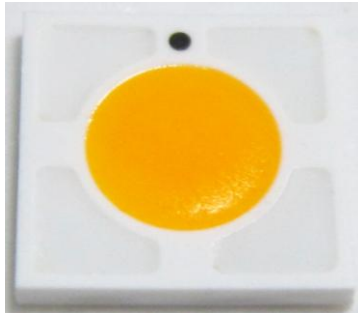




ProLight Opto
Technology Corporation



**ProLight PEA2-3FNE
3W Neutral White AC LED
Technical Datasheet
Version: 1.3**

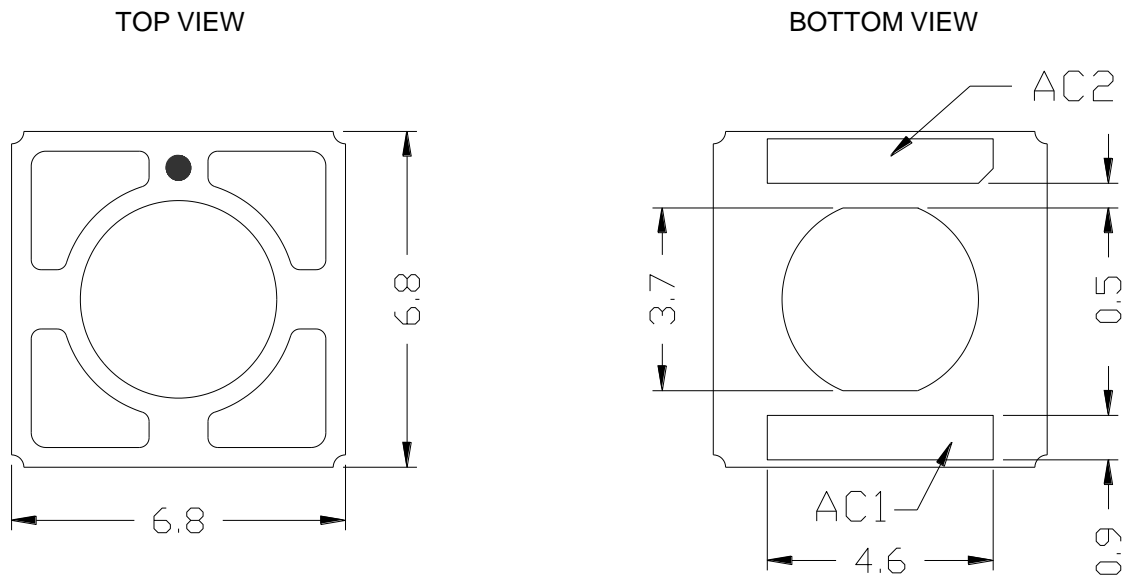
Features

- High Color rendering index
- Follow ANSI C78.788.2008 Chromaticity co-ordinates
- High flux per LED
- Good color uniformity
- Industry best moisture sensitivity level - JEDEC Level 1
- RoHS compliant
- More energy efficient than incandescent and most halogen lamps
- Instant light (less than 100ns)
- No UV

Typical Applications

- G9

Emitter Mechanical Dimensions



Notes:

1. Electrical insulation between the case and the board is required. Do not electrically connect either the AC1 or AC2 to the slug.
2. Drawing not to scale.
3. All dimensions are in millimeters.
4. Unless otherwise indicated, tolerances are $\pm 0.10\text{mm}$.
5. Please do not bend the leads of the LED, otherwise it will damage the LED.
6. **Please do not use a force of over 3kgf impact or pressure on the LED, otherwise it will cause a catastrophic failure.**

*The appearance and specifications of the product may be modified for improvement without notice.

Flux Characteristics at 12mA-rms, T_J = 25°C

Radiation Pattern	Color	Part Number Emitter	Lumious Flux Φ_v (lm)		CRI Typical
			Minimum	Typical	
Flat	Neutral White	PEA2-3FNE	147.7	160	80

- ProLight maintains a tolerance of $\pm 10\%$ on flux and power measurements.
- Please do not drive at rated current more than 1 second without proper heat sink.

Optical Characteristics at 12mA-rms, T_J = 25°C

Color	Color Temperature CCT			Total included Angle (degrees) $\theta_{0.90V}$	Viewing Angle (degrees) $2 \theta_{1/2}$	Thermal Resistance Junction to Slug ($^{\circ}C/W$)
	Min.	Typ.	Max.			
Neutral White	3710 K	4000 K	4260 K	160	140	8

- ProLight maintains a tolerance of $\pm 5\%$ for CCT measurements.

Electrical Characteristics at 12mA-rms, T_J = 25°C

Color	Forward Voltage V _F (V)		
	Min.	Typ.	Max.
Neutral White	200	210	220

- ProLight maintains a tolerance of $\pm 5\%$ for Voltage measurements.

Absolute Maximum Ratings

Parameter	Neutral White
DC Forward Current (mA)	13.2
Peak Pulsed Forward Current (mA)	26.4 (less than 1/10 duty cycle@1KHz)
ESD Sensitivity (HBM per MIL-STD-883E Method 3015.7)	> ±500V
LED Junction Temperature	≤115°C
Operating Board Temperature at Maximum DC Forward Current	85°C
Storage Temperature	-40°C - 85°C
Soldering Temperature	JEDEC 020c 260°C
Allowable Reflow Cycles	1

Photometric Luminous Flux Bin Structure

Color	Bin Code	Minimum Photometric Flux (lm)	Maximum Photometric Flux (lm)	Available Color Bins
Neutral White	W1	147.7	168.4	All
	W2	168.4	192	[1]
	X1	192	218.9	[1]

- ProLight maintains a tolerance of ± 10% on flux and power measurements.
- The flux bin of the product may be modified for improvement without notice.
- ^[1] The rest of color bins are not 100% ready for order currently. Please ask for quote and order possibility.

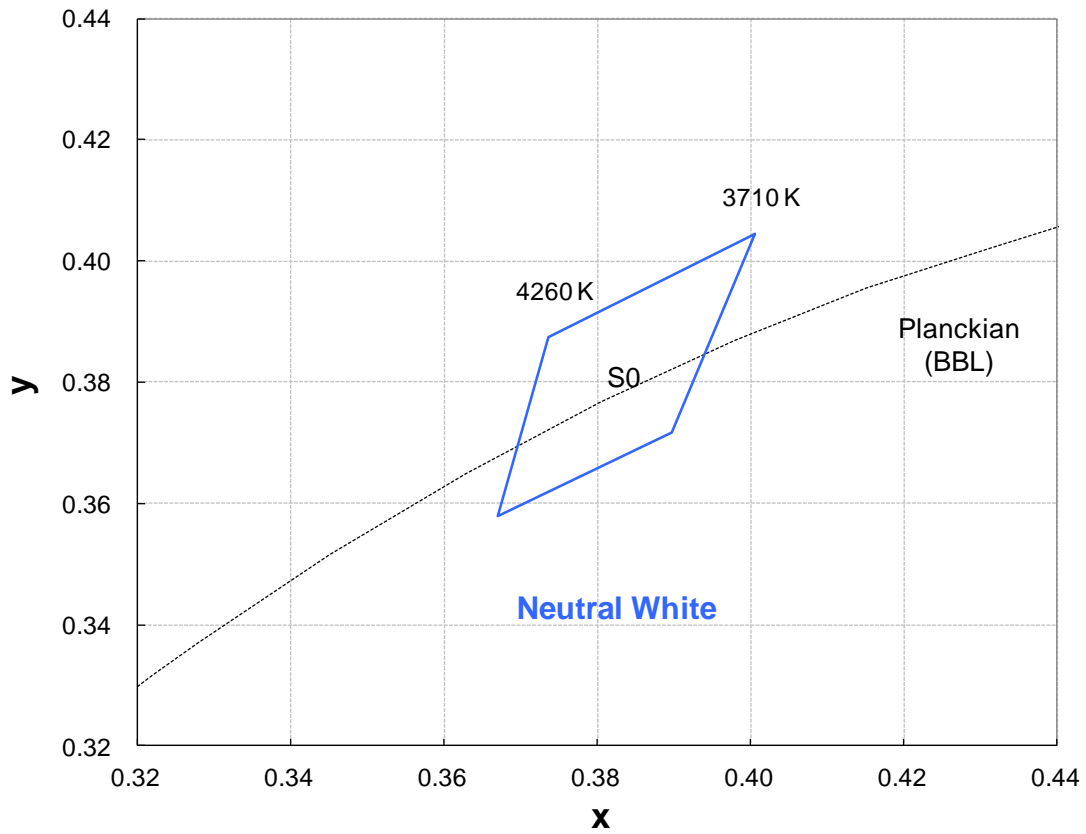
Voltage Bin Structure

Color	Bin Code	Minimum Voltage[RMS]	Maximum Voltage[RMS]
Neutral White	A	200	210
	B	210	220

- ProLight maintains a tolerance of ± 5% for Voltage measurements.

Color Bins

Neutral White Binning Structure Graphical Representation



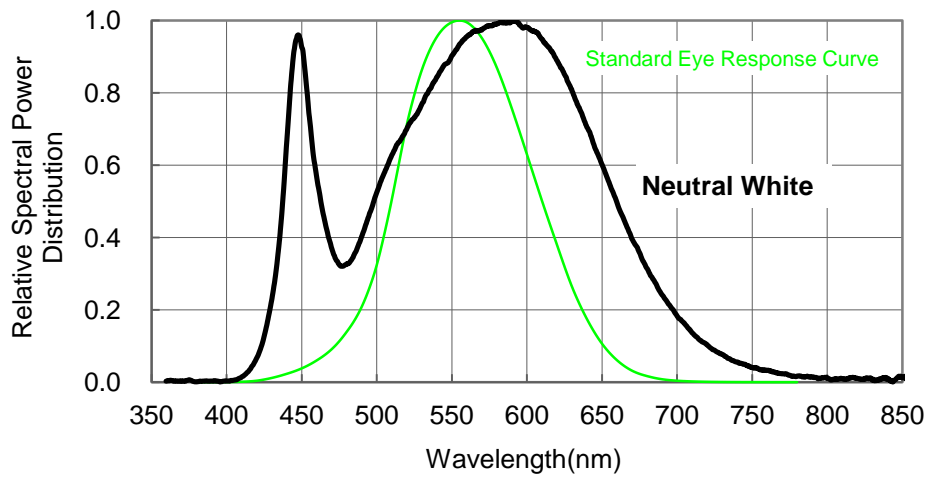
Neutral White Bin Structure

Bin Code	x	y	Typ. CCT (K)
S0	0.4006	0.4044	4000
	0.3736	0.3874	
	0.3670	0.3578	
	0.3898	0.3716	

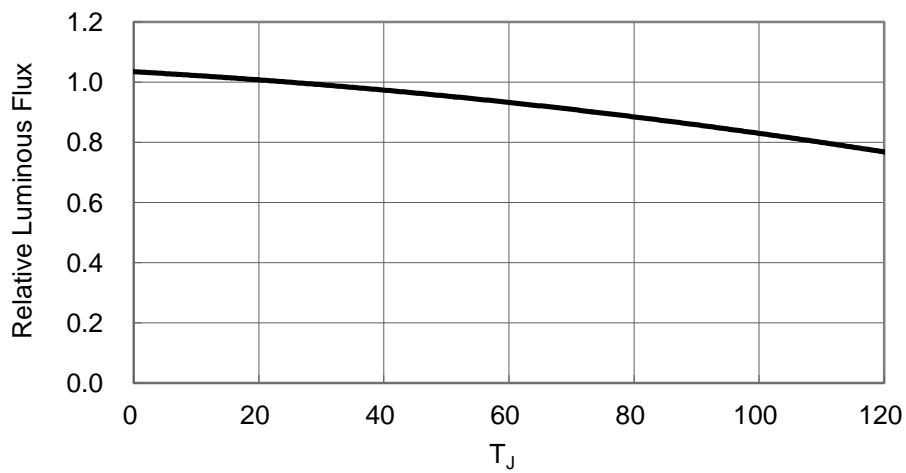
- Tolerance on each color bin (x , y) is ± 0.01

Color Spectrum, $T_J = 25^\circ\text{C}$

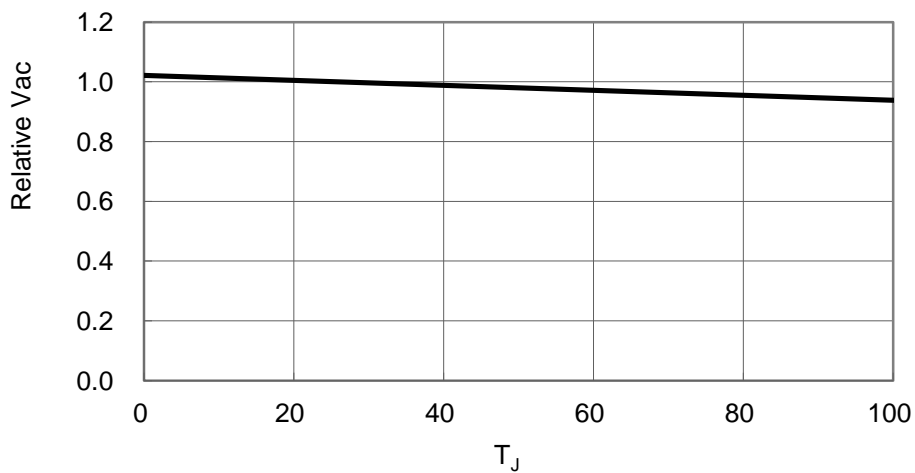
1. Neutral White



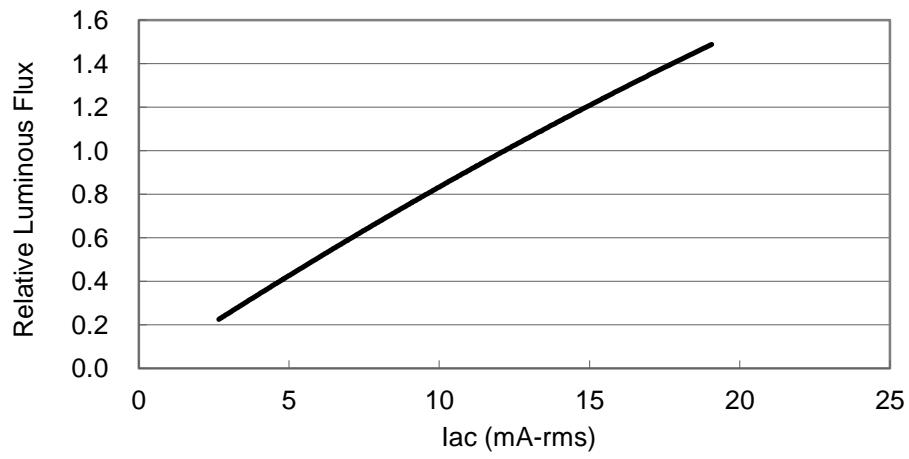
T_J VS Relative Luminous Flux



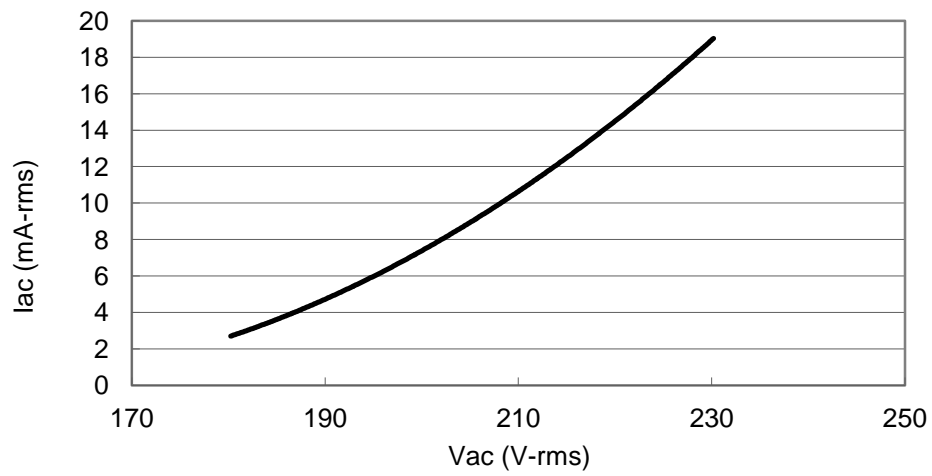
T_J VS Relative Vac



lac VS Relative Luminous Flux



lac VS Vac



Reference Resistors Table

220V / 50Hz @ T _j = 25 °C			
Resistor	Lumen	Power	Effeciency
3000	89	1.4	64.8
2500	97	1.5	63.6
2000	108	1.7	62.4
1500	120	2.0	61.2
1000	137	2.3	59.1
800	149	2.6	57.9

230V / 50Hz @ T _j = 25 °C			
Resistor	Lumen	Power	Effeciency
4000	94	1.5	63.4
3500	102	1.6	62.4
3000	111	1.8	61.5
2500	120	2.0	60.8
2000	136	2.3	59.4
1500	154	2.7	57.5

Note: With the increase of case temperature, Power(W) will increase accordingly.

Moisture Sensitivity Level - JEDEC Level 1

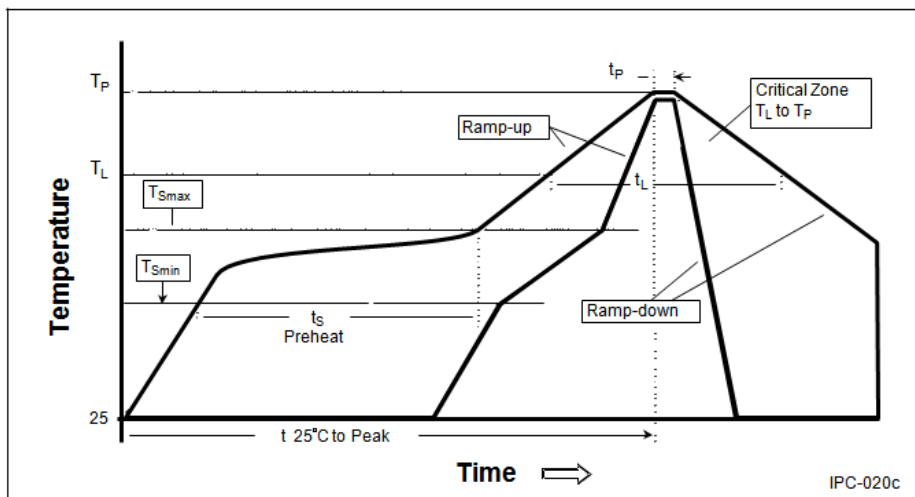
Level	Floor Life		Soak Requirements			
			Standard		Accelerated Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions
1	Unlimited	≤30°C / 85% RH	168 +5/-0	85°C / 85% RH	NA	NA

- The standard soak time includes a default value of 24 hours for semiconductor manufacture's exposure time (MET) between bake and bag and includes the maximum time allowed out of the bag at the distributor's facility.
- Table below presents the moisture sensitivity level definitions per IPC/JEDEC's J-STD-020C.

Level	Floor Life		Soak Requirements			
			Standard		Accelerated Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions
1	Unlimited	≤30°C / 85% RH	168 +5/-0	85°C / 85% RH	NA	NA
2	1 year	≤30°C / 60% RH	168 +5/-0	85°C / 60% RH	NA	NA
2a	4 weeks	≤30°C / 60% RH	696 +5/-0	30°C / 60% RH	120 +1/-0	60°C / 60% RH
3	168 hours	≤30°C / 60% RH	192 +5/-0	30°C / 60% RH	40 +1/-0	60°C / 60% RH
4	72 hours	≤30°C / 60% RH	96 +2/-0	30°C / 60% RH	20 +0.5/-0	60°C / 60% RH
5	48 hours	≤30°C / 60% RH	72 +2/-0	30°C / 60% RH	15 +0.5/-0	60°C / 60% RH
5a	24 hours	≤30°C / 60% RH	48 +2/-0	30°C / 60% RH	10 +0.5/-0	60°C / 60% RH
6	Time on Label (TOL)	≤30°C / 60% RH	Time on Label (TOL)	30°C / 60% RH	NA	NA

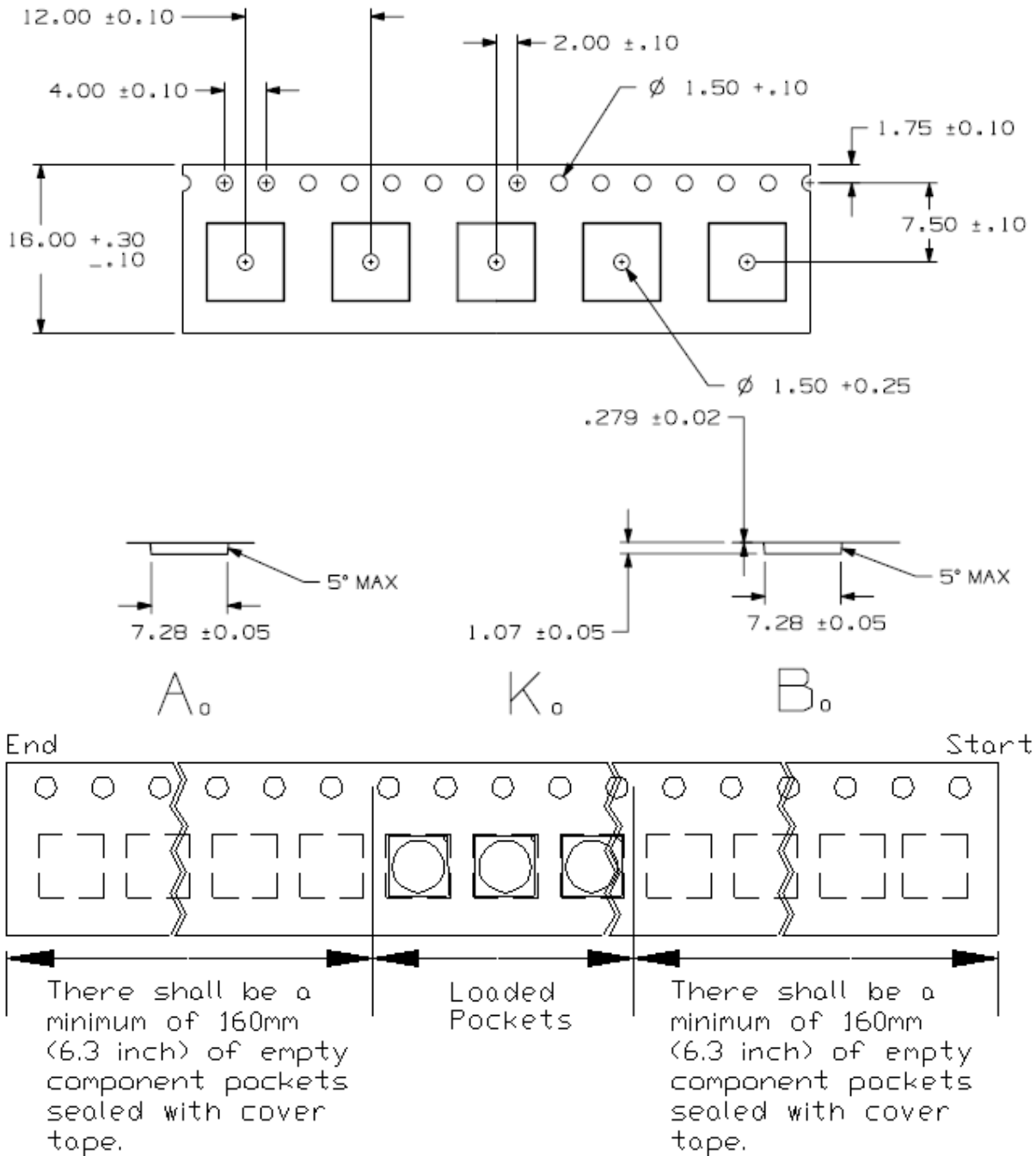
Reflow Soldering Condition

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate (T_{Smax} to T_P)	3°C / second max.	3°C / second max.
Preheat <ul style="list-style-type: none"> - Temperature Min (T_{Smin}) - Temperature Max (T_{Smax}) - Time (t_{Smin} to t_{Smax}) 	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: <ul style="list-style-type: none"> - Temperature (T_L) - Time (t_L) 	183°C 60-150 seconds	217°C 60-150 seconds
Peak/Classification Temperature (T_P)	240°C	260°C
Time Within 5°C of Actual Peak Temperature (t_p)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



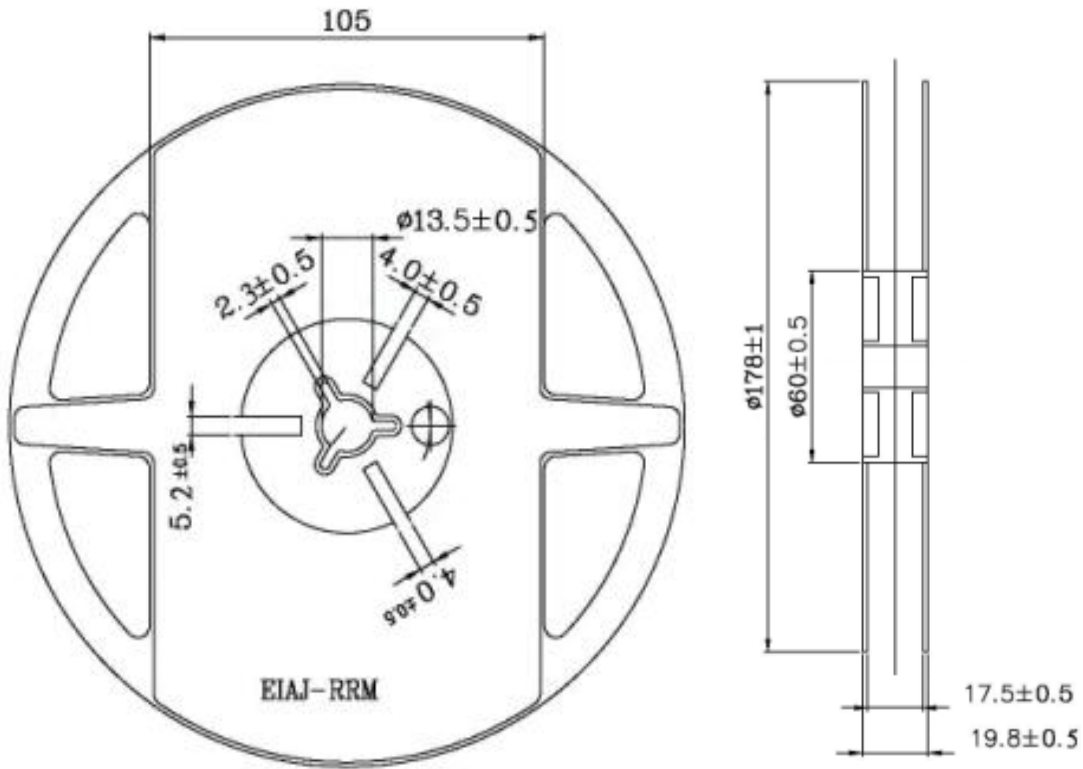
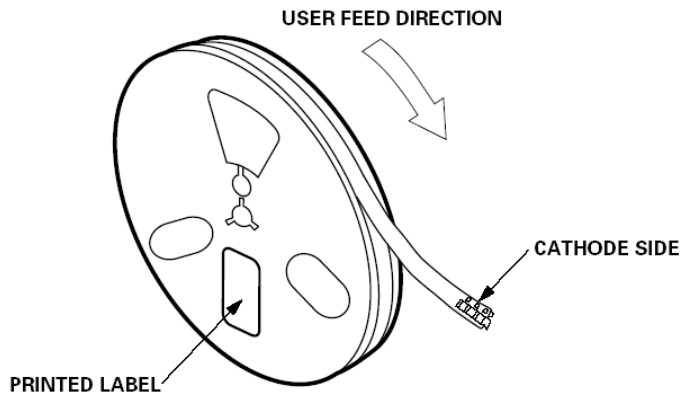
- We recommend using the M705-S101-S4 solder paste from SMIC (Senju Metal Industry Co., Ltd.) for lead-free soldering.
- Do not use solder pastes with post reflow flux residue > 47%. (58Bi-42Sn eutectic alloy, etc) This kind of solder pastes may cause a reliability problem to LED.
- All temperatures refer to topside of the package, measured on the package body surface.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than one times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

Emitter Reel Packaging



- Notes:
1. Drawing not to scale.
 2. All dimensions are in millimeters.
 3. Unless otherwise indicated, tolerances are ± 0.10mm.

Emitter Reel Packaging



- Notes:
1. Empty component pockets sealed with top cover tape.
 2. 250, 500 and 1000 pieces per reel.
 3. Drawing not to scale.
 4. All dimensions are in millimeters.

Precaution for Use

- Storage
Please do not open the moisture barrier bag (MBB) more than one week. This may cause the leads of LED discoloration. We recommend storing ProLight's LEDs in a dry box after opening the MBB. The recommended storage conditions are temperature 5 to 30°C and humidity less than 40% RH. It is also recommended to return the LEDs to the MBB and to reseal the MBB.
- The slug is not electrically neutral. Therefore, we recommend to isolate the heat sink.
- **We recommend using the M705-S101-S4 solder paste from SMIC (Senju Metal Industry Co., Ltd.) for lead-free soldering.**
- **Do not use solder pastes with post reflow flux residue >47%. (58Bi-42Sn eutectic alloy, etc) This kind of solder pastes may cause a reliability problem to LED.**
- Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temperature after soldering.
- Please avoid rapid cooling after soldering.
- Components should not be mounted on warped direction of PCB.
- **Repairing should not be done after the LEDs have been soldered.**
- This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When cleaning is required, isopropyl alcohol should be used.
- When the LEDs are illuminating, operating current should be decided after considering the package maximum temperature.
- The appearance, specifications and flux bin of the product may be modified for improvement without notice. Please refer to the below website for the latest datasheets.
<http://www.prolightopto.com/>

Handling of Silicone Lens LEDs

Notes for handling of silicone lens LEDs

- Please do not use a force of over 3kgf impact or pressure on the LED, otherwise it will cause a catastrophic failure.
- The LEDs should only be picked up by making contact with the sides of the LED body.
- Avoid touching the silicone especially by sharp tools such as Tweezers.
- Avoid leaving fingerprints on the silicone.
- Please store the LEDs away from dusty areas or seal the product against dust.
- When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the silicone must be prevented.
- Please do not mold over the silicone with another resin. (epoxy, urethane, etc)